

IN THE SPECIFICATION

Please replace the paragraphs [0029] and [0030] with the following amended paragraphs:

[0029] **Figure 9A** is a 3D illustration of one embodiment of a pumping plate having a short-skirt. **Figure 9B** is a cross-section illustration of the one embodiment of the pumping plate having the short-skirt. The skirt 922 and a number of holes, here vertical slots [[928,]] 930, can balance the local effects of higher or lower heat absorption resulting from non-uniform conditions within the process chamber interior 816 (**Figure 8A**). However, it is also important to minimize the temperatures within the pumping plate 912 during processing. Along with lower pumping plate 912 temperatures, temperature uniformity is also important during processing. Lowering the temperatures in the pumping plate 912 during processing can reduce the possibility of the pumping plate 912 material adding impurities into the chamber process 800 (**Figure 8A**) to contaminate the wafer or the wafer film being deposited. The pumping plate 912 can be manufactured from aluminum that can have an anodized coating, however one skilled in the arts should realize that other materials such as stainless steel can be used. Higher temperatures in the pumping plate 912 can crack or flake coatings (if used) on the pumping plate 912 such as the anodize coating. With the underlying bare metal exposed, it is possible for some of the metal to become airborne as contaminants.

[0030] Referring to **Figure 9B**, when removing the section of the skirt 926 (dashed) at the wafer access slot 928, as opposed to providing a complete horizontal slot, heat does not have

to travel 929 around the slot ~~[[924]]~~ 928 to reach the flanges 917. Such thermal flow would create a “hot spot” in the bottlenecked areas between the slots 930 adjacent to the wafer access slot 928. With this section 926 of the skirt 922 removed, heat is not absorbed in this area, and therefore will not add to the heat flow at adjacent slot areas 932 and which would increase the temperatures. In addition, with the wafer access slot 821 open at the aft end 830, the overall length L of the skirt can be shortened (short skirt). This can allow for skirt length L to be driven by the hole size, here the slot major axis, necessary to line up the slit valve 818 (**Figure 8B**). This skirt slot axial lineup with the slit valve, along the sum of the areas of the slots approximately equaling the area of the slit valve, being a rule of thumb that can provide approximate compensation for the heat loss into the slit valve 818.